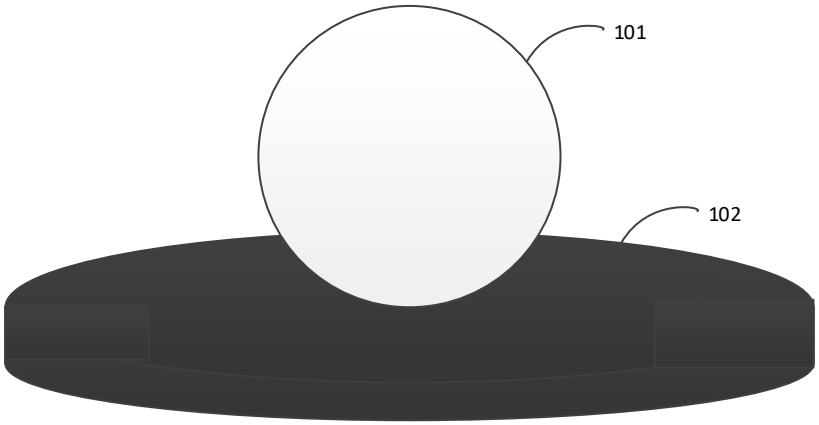

FIG. 1

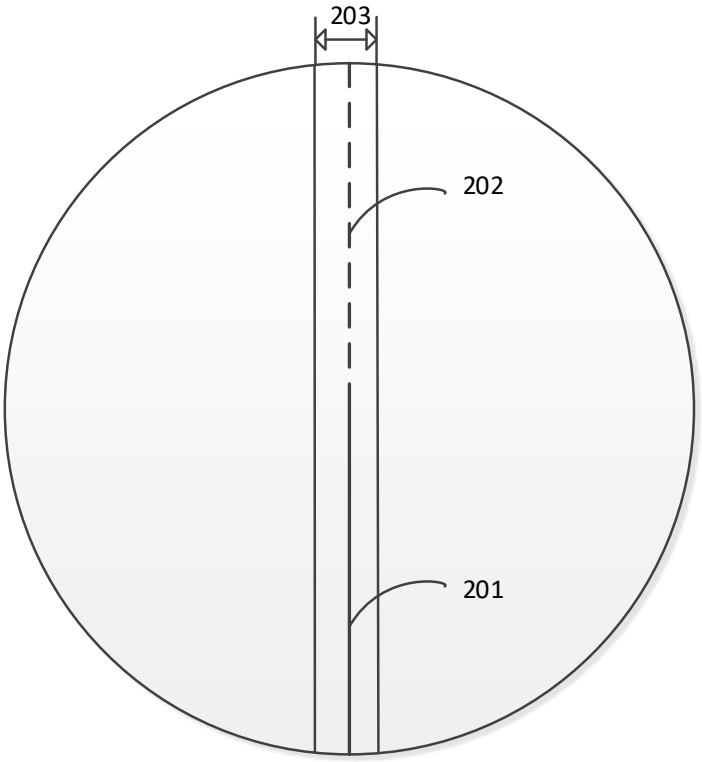

FIG. 2

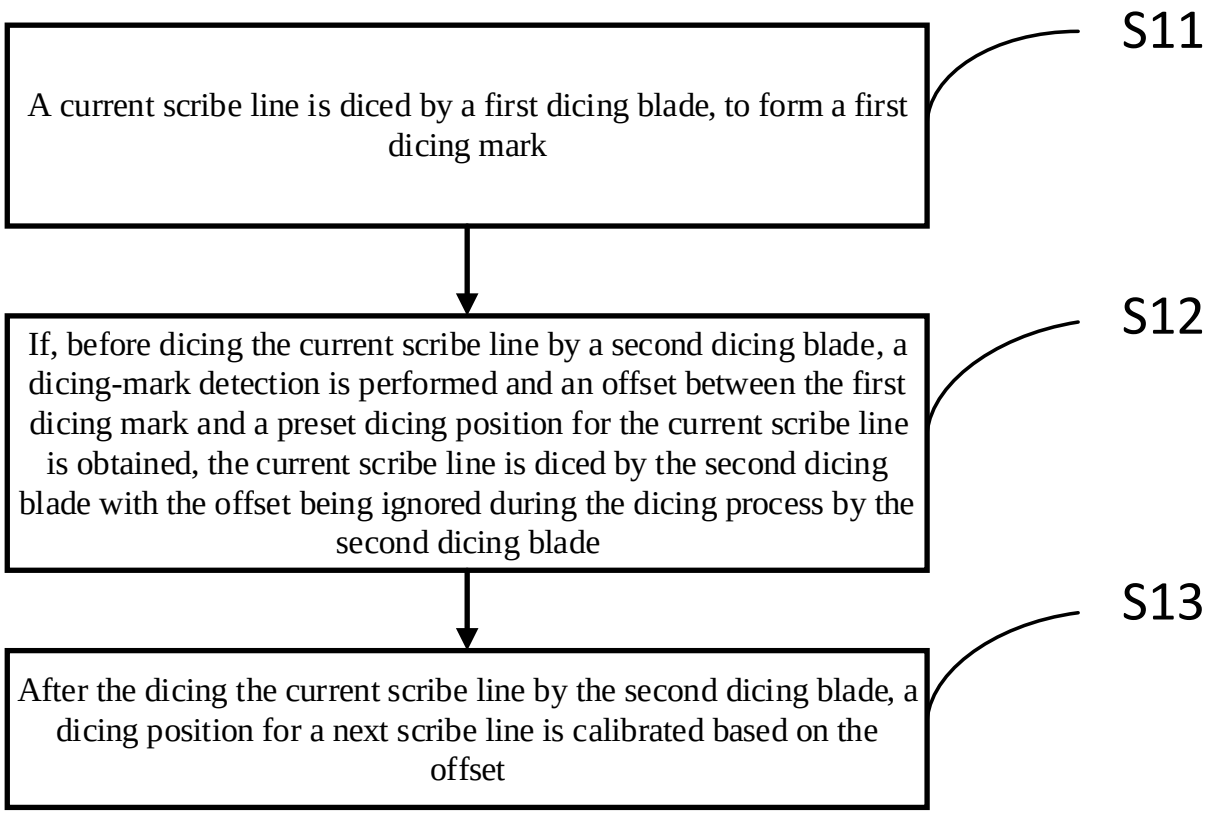
A current scribe line is diced by a first dicing blade, to form a first dicing mark
S11
If, before dicing the current scribe line by a second dicing blade, a dicing-mark detection is performed and an offset between the first dicing mark and a preset dicing position for the current scribe line is obtained, the current scribe line is diced by the second dicing blade with the offset being ignored during the dicing process by the second dicing blade
S12
After the dicing the current scribe line by the second dicing blade, a dicing position for a next scribe line is calibrated based on the offset
S13

FIG. 3

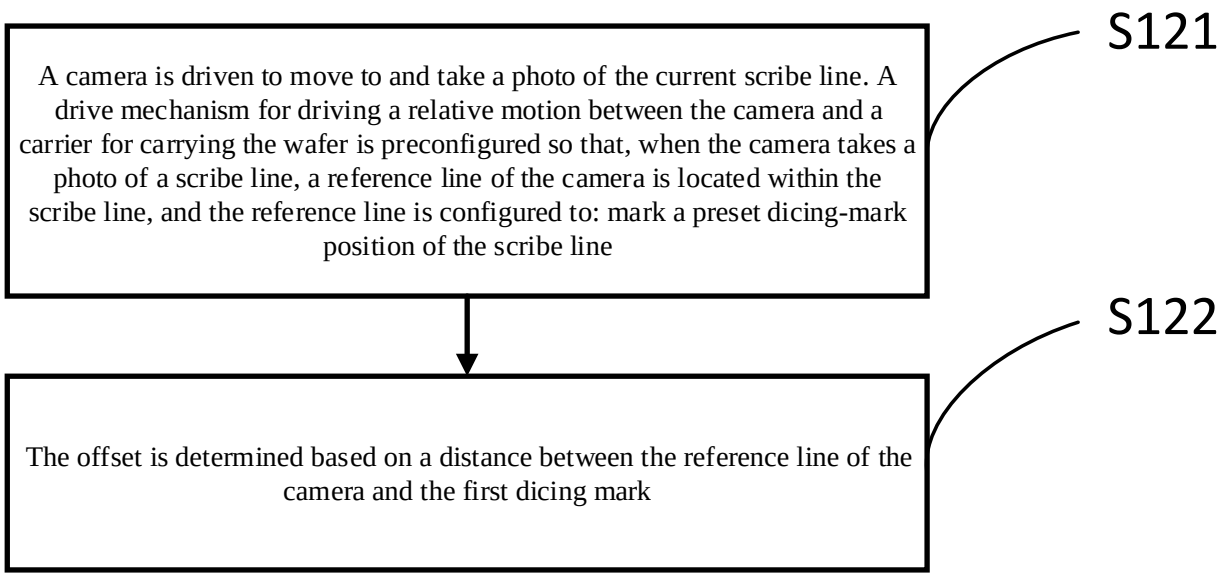
A camera is driven to move to and take a photo of the current scribe line. A drive mechanism for driving a relative motion between the camera and a carrier for carrying the wafer is preconfigured so that, when the camera takes a photo of a scribe line, a reference line of the camera is located within the scribe line, and the reference line is configured to: mark a preset dicing-mark position of the scribe line
S121
The offset is determined based on a distance between the reference line of the camera and the first dicing mark
S122

FIG. 4

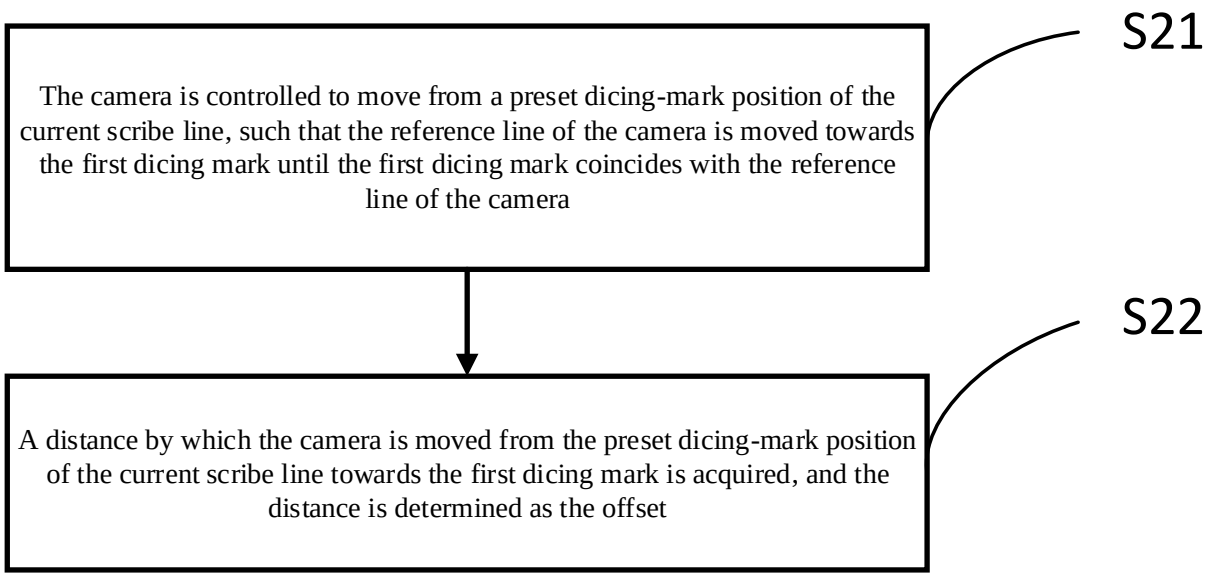
S21
The camera is controlled to move from a preset dicing-mark position of the current scribe line, such that the reference line of the camera is moved towards the first dicing mark until the first dicing mark coincides with the reference line of the camera
S22
A distance by which the camera is moved from the preset dicing-mark position of the current scribe line towards the first dicing mark is acquired, and the distance is determined as the offset

FIG. 5

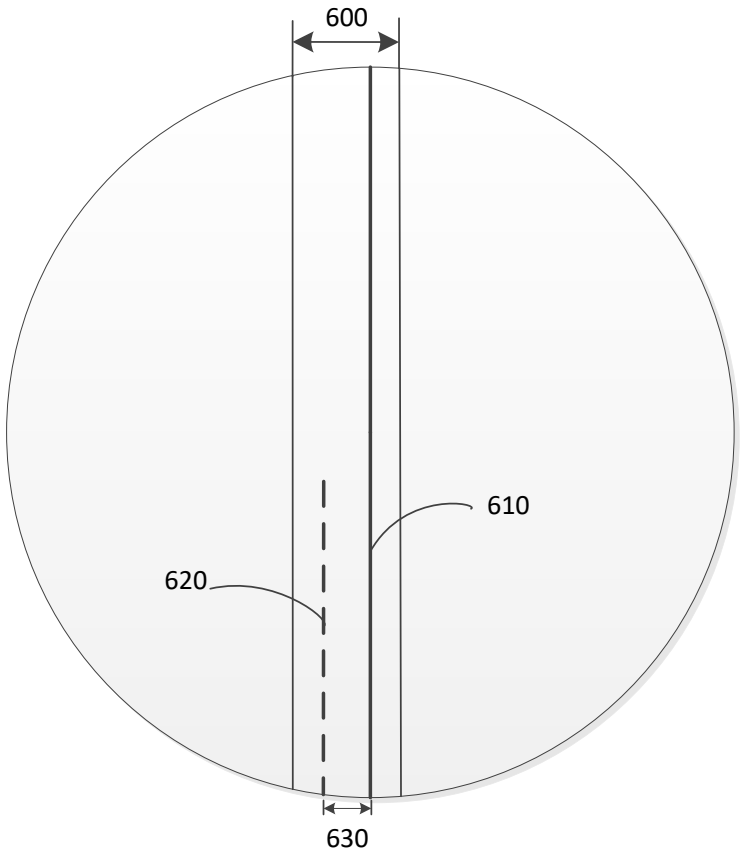

FIG. 6

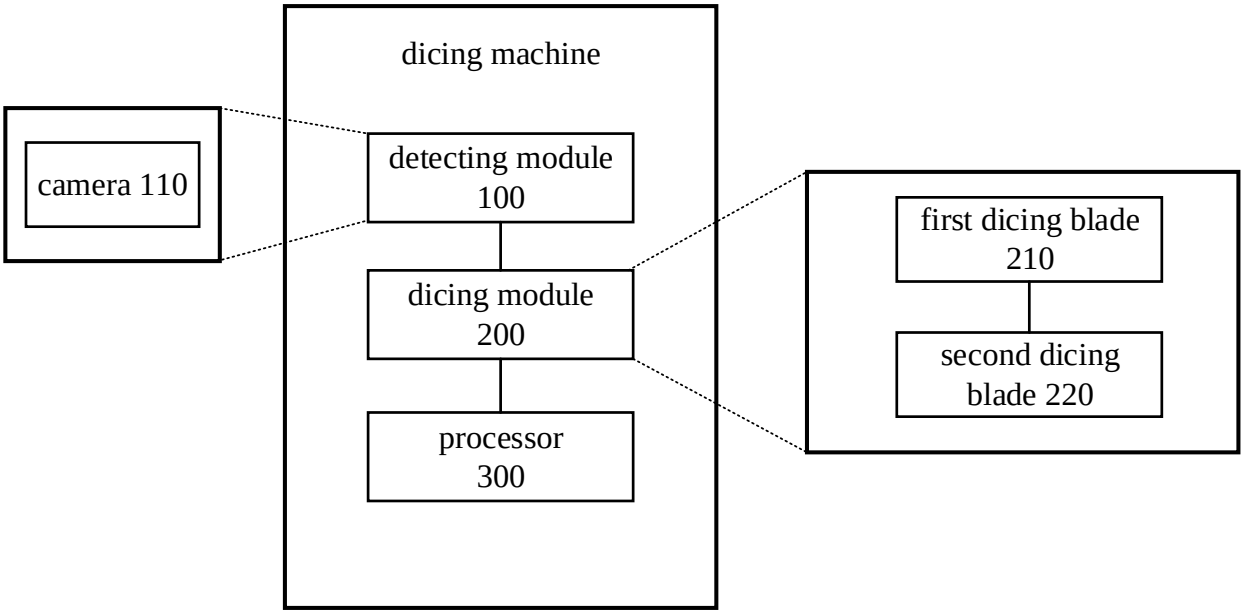
dicing machine
camera 110
detecting module 100
dicing module 200
processor 300
first dicing blade 210
second dicing blade 220

FIG. 7